VS-FCSP0730TR

Vishay Semiconductors

FlipKY[®], Chip Scale Package Schottky Barrier Rectifier, 0.75 A



FlipKY[®]

IF(AV) 0.75 A VR 30 V VF at IF 0.37 V IRM max. at 25 °C 50 μA IRM max. at 125 °C 15 mA TJ max. 150 °C EAS 5 mJ

FEATURES

- Ultra low V_F to footprint area
- Very low profile (< 0.6 mm)
- Low thermal resistance
- · Supplied tested and on tape and reel
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Reverse polarity protection
- · Current steering
- Freewheeling
- Flyback
- Oring

DESCRIPTION

Vishay's FlipKY[®] product family utilizes wafer level chip scale packaging to deliver Schottky diodes with the lowest V_F to PCB footprint area in industry. The three pad 0.9 mm x 1.2 mm devices can deliver up to 0.75 A and occupy only 1.08 mm² of board space. The anode and cathode connections are made through solder bump pads on one side of the silicon enabling designers to strategically place the diodes on the PCB. This design not only minimizes board space but also reduces thermal resistance and inductance, which can improve overall circuit efficiency.

Typical applications include hand-held, portable equipment such as cell phones, MP3 players, bluetooth, GPS, PDAs, and portable hard disk drives where space savings and performance are crucial.

MAJOR RATINGS AND CHARACTERISTICS				
SYMBOL	CHARACTERISTICS	MAX.	UNITS	
V _{RRM}		30	V	
I _{F(AV)}	Rectangular waveform	0.75	٨	
I _{FSM}		190	A	
V _F	0.75 A _{pk} , T _J = 125 °C	0.37	V	
TJ		- 55 to 150	°C	

VOLTAGE RATINGS				
PARAMETER	SYMBOL	VS-FCSP0730TR	UNITS	
Maximum DC reverse voltage	V _R	30	V	
Maximum working peak reverse voltage	V _{RWM}	30	v	

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COMPLIANT





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ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current	I _{F(AV)}	50 % duty cycle at T_{PCB} = 127 °C, rectangular waveform		0.75	
Maximum peak one cycle	I =0.1	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with	190	А
non-repetitive surge current at 25 °C	IFSM	10 ms sine or 6 ms rect. pulse	rated V _{RRM} applied	10	
Non-repetitive avalanche energy	E _{AS}	T _J = 25 °C, I _{AS} = 2.0 A, L = 5.0 mH		5	mJ
Repetitive avalanche current	I _{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum V_A = 1.5 x V_R typical		0.5	А

ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		TYP.	MAX.	UNITS
Maximum forward voltage drop See fig. 1		0.75 A	T ₁ = 25 °C	0.43	0.43 0.47	
	V _{FM} ⁽¹⁾	1.5 A	- 1j = 25 C	0.50	0.54	v
	VFM (*)	0.75 A	T 105 00 0.33 0.	0.37	v	
		1.5 A	− T _J = 125 °C	0.43	0.47 0.54 0.37 0.47 50 15 90	
Maximum reverse leakage current	I _{BM} ⁽¹⁾	T _J = 25 °C	$V_{\rm B}$ = Rated $V_{\rm B}$	10	50	μA
See fig. 2	IRM \''	T _J = 125 °C	$v_{\rm R} = haleu v_{\rm R}$	5	5 15	mA
Maximum junction capacitance	CT	$V_{R} = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz), 25 °C		-	90	pF
Maximum voltage rate of charge	dV/dt	Rated V _R		-	10 000	V/µs

Note

⁽¹⁾ Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T _J ⁽¹⁾ , T _{Stg}		- 55 to 150	°C
Typical thermal resistance, junction to PCB	R _{thJL} ⁽²⁾	DC operation	35	°C/W
Typical thermal resistance, junction to ambient	R _{thJA}		150	0/11

Notes

(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

⁽²⁾ Mounted on minimum footprint PCB



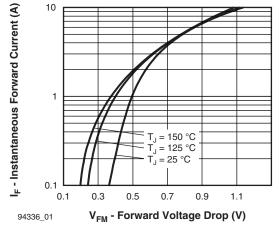
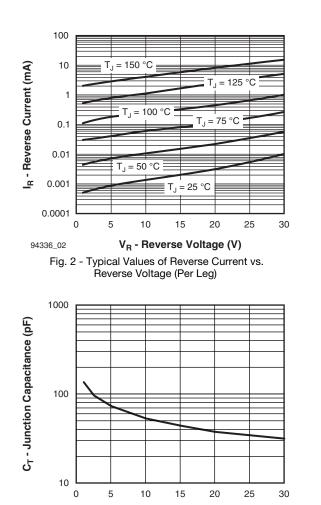


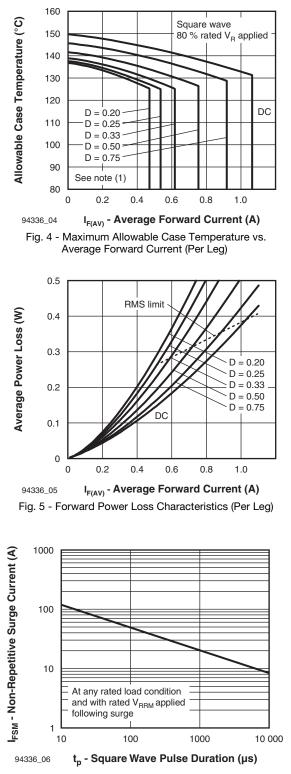
Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

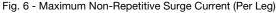




V_R - Reverse Voltage (V)

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Note

⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}/D$) (see fig. 6); Pd_{REV} = Inverse power loss = $V_{R1} \times I_R$ (1 - D); I_R at 80 % V_R applied

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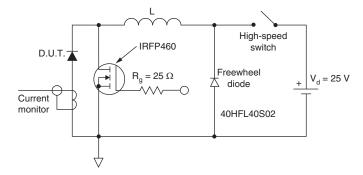


Fig. 7 - Unclamped Inductive Test Circuit

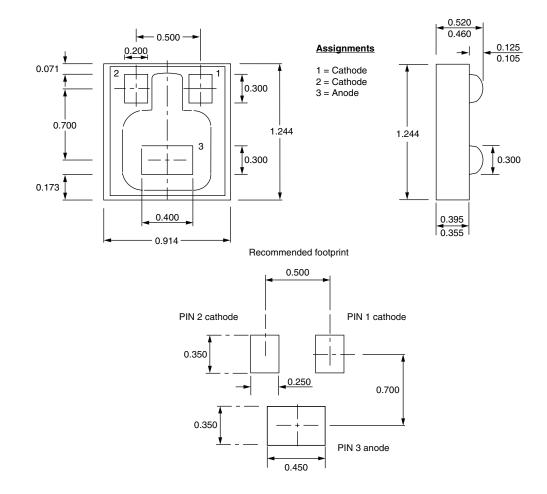
LINKS TO RELATED DOCUMENTS		
Dimensions	www.vishay.com/doc?95049	
Part marking information	www.vishay.com/doc?95060	
Packaging information	www.vishay.com/doc?95062	

Vishay High Power Products



FlipKY[®] 0.5 A/0.75 A

DIMENSIONS in millimeters



Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Controlling dimension: millimeter



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